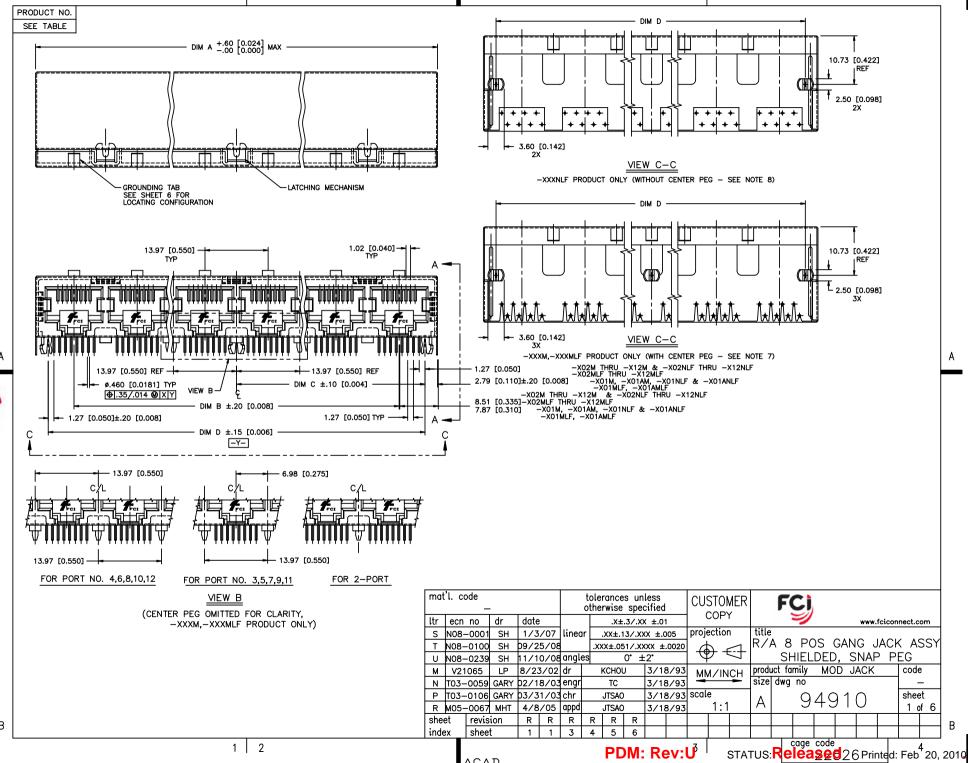
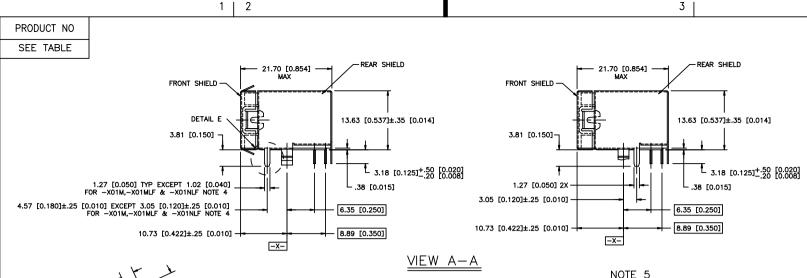
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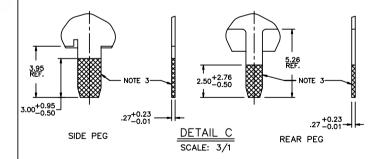
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NOTES:

3.05 [0.12] REF. NO BOTTOM SPRING (BOTTOM SPRING NO MORE THAN 5° BEND OUT WAS BEND BACK)

P/N-X03N-ALF ONLY



1. RECOMMENDED P.C.B. THICKNESS 1.60 [0.063].

2. CONTACTS: PHOS BRONZE ALLOY UNS-C51000, Ø 0.460 [0.0181] ROUND WIRE, PLATING SEE TABLE.

(3) SHIELDING MAT'L: .25 [0.010] THICK BRASS ALLOY. SHIELDING PLATING: FOR 94910-XXXM: 2.54uM/100u" MIN BRIGHT TIN-LEAD PLATED OVER 0.76uM/30u" MIN NICKEL UNDERPLATING PER BUS-15-002/M.

FOR 94910-XXXNLF: 0.76uM/30u" MIN NICKEL PLATING, WITH SELECTIVE TIN ON SOLDER TAILS, SEE DETAIL É.

SHIELDING PLATING: FOR 94910-XXXMLF: 2.54uM/100u" MIN BRIGHT PURE TIN PLATED OVER 0.76uM/30u" MIN NICKEL UNDERPLATING PER BUS-15-002/M.

(4) SPECIALLY FOR ONE-PORT P/N 94910-X01M,-X01MLF & 94910-X01NLF ONLY. SOLDER TAIL OF SHIELD IS 1.02 [0.040] WIDE, DISTANCE FROM PCB PEG TO THE SOLDER TAIL IS 3.05 [0.120].

(5) SPECIALLY FOR ONE-PORT P/N 94910-X01AM.-X01AMLF& 94910-X01ANLF ONLY. SOLDER TAIL OF SHIELD IS 1.27 [0.050] WIDE, DISTANCE FROM PCB PEG TO THE SOLDER TAIL IS 3.05 [0.120].

6. ALL DIMENSIONS IN MILLIMETERS/INCHES.

(7) CENTER PEG FOR 8-PORTS AND ABOVE, (-XXXM, -XXXMLF PRODUCT ONLY).

(8.) NO CENTER PEG AVAILABLE ON —XXXNLF PRODUCT.

(9), 'LF" SUFFIX AT THE END OF PART NUMBER IS LEAD FREE.

10. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 15 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.5mm MINIMUM THICK CIRCUIT BOARD. SEE APLICATION NOTES/PROCEDURES IF THEY ARE AVAILABLE.

11. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008

(12) PLATING OPTIONS: MAY BE EITHER GOLD OR GXT PLATED AT MANUFACTURER'S OPTION.

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PRODUCT No.	No. OF PORTS	DIM A +.60 [0.024]	DIM B	DIM C±.10 [0.004]	DIM D±.15 [0.006]	GROUND LEG NO. ON THE BACK (VIEW B)	NOTE
94910-X01M	1	15.74 [0.620]		5.72 [0.225]	11.43 [0.450]	NONE	NOTE 4
94910-X01AM	1	15.74 [0.620]		5.72 [0.225]	11.43 [0.450]	NONE	NOTE 5
94910-X04M	4	58.92 [2.320]	41.91 [1.650]	26.67 [1.050]	53.34 [2.100]	3	
94910-X08M	8	114.80 [4.520]	97.79 [3.850]	54.61 [2.150]	109.22 [4.300]	3	
94910-X01MLF	1	15.74 [0.620]		5.72 [0.225]	11.43 [0.450]	NONE	NOTE 4
94910-X01AMLF	1	15.74 [0.620]		5.72 [0.225]	11.43 [0.450]	NONE	NOTE 5
94910-X04MLF	4	58.92 [2.320]	41.91 [1.650]	26.67 [1.050]	53.34 [2.100]	3	
94910-X08MLF	8	114.80 [4.520]	97.79 [3.850]	54.61 [2.150]	109.22 [4.300]	3	
94910-X11MLF	1	15.74 [0.620]		5.72 [0.225]	11.43 [0.450]	NONE	NOTE 4
94910-X11AMLF	1	15.74 [0.620]		5.72 [0.225]	11.43 [0.450]	NONE	NOTE 5
94910-X14MLF	4	58.92 [2.320]	41.91 [1.650]	26.67 [1.050]	53.34 [2.100]	3	
94910-X18MLF	8	114.80 [4.520]	97.79 [3.850]	54.61 [2.150]	109.22 [4.300]	3	

- O: MEETS WAVE SOLDER PROCESS PRODUCT NO.

1: MEETS PIP PROCESS PRODUCT NO.

PLATING CODE X	PLATING 12
0	.76uM/30u" G.X.T.
1	.38uM/15u" GOLD
3	.76uM/30u" GOLD
5	1.27uM/50u" GOLD

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PRODUCT No.	PORTS	DIM A -0	DIM B±.20 [0.008]	DIM C±.10 [0.004]	DIM D±.15 [0.006]	THE BACK (VIEW B)	
94910-X01NLF	1	15.74 [0.620]		5.72 [0.225]	11.43 [0.450]	NONE	NOTE 4
94910-X01ANLF	1	15.74 [0.620]		5.72 [0.225]	11.43 [0.450]	NONE	NOTE 5
94910-X04NLF	4	58.92 [2.320]	41.91 [1.650]	26.67 [1.050]	53.34 [2.100]	3	
94910-X08NLF	8	114.80 [4.520]	97.79 [3.850]	54.61 [2.150]	109.22 [4.300]	3	
94910-X11NLF	1	15.74 [0.620]		5.72 [0.225]	11.43 [0.450]	NONE	NOTE 4
94910-X11ANLF	1	15.74 [0.620]		5.72 [0.225]	11.43 [0.450]	NONE	NOTE 5
94910-X14NLF	4	58.92 [2.320]	41.91 [1.650]	26.67 [1.050]	53.34 [2.100]	3	
94910-X18NLF	8	114.80 [4.520]	97.79 [3.850]	54.61 [2.150]	109.22 [4.300]	3	·

- 0: MEETS WAVE SOLDER PROCESS PRODUCT NO.

1: MEETS PIP PROCESS PRODUCT NO.

PLATING CODE X	PLATING 12
0	.76uM/30u" G.X.T.
1	.38uM/15u" GOLD
3	.76uM/30u" GOLD
5	1.27uM/50u" GOLD

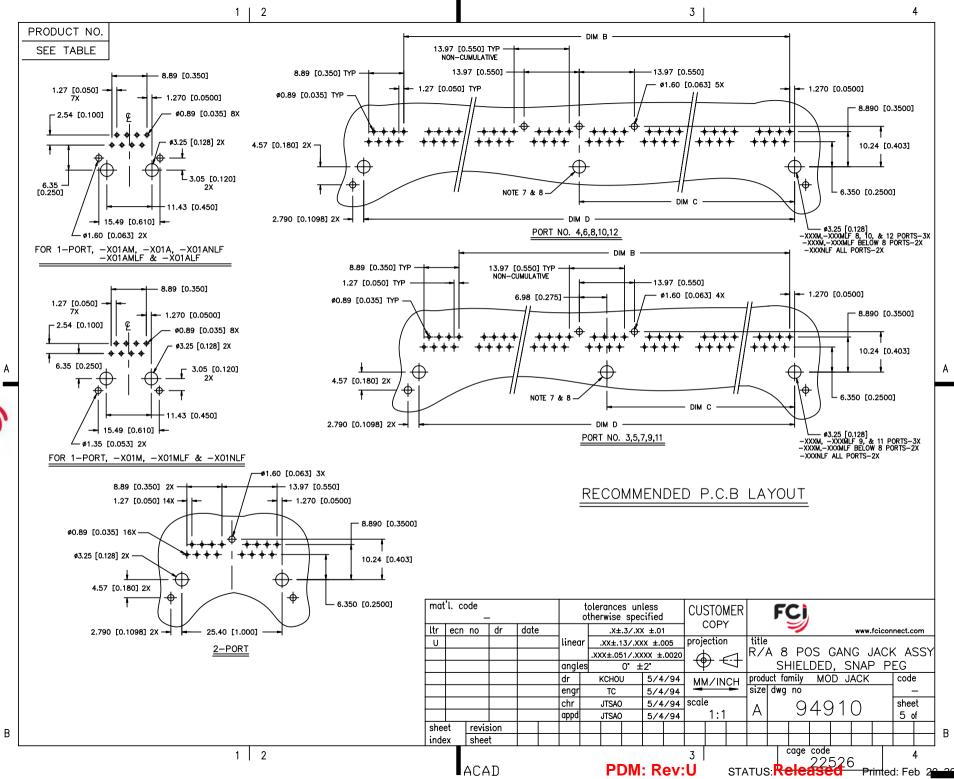
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LATCHING AND GROUNDING TAB LOCATING CONFIGURATION

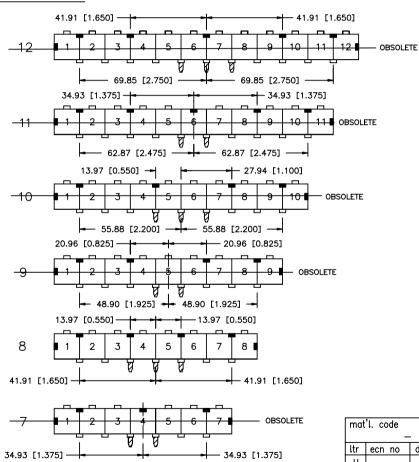
■ INDICATES LATCHING TAB (SEE SHEET 1)

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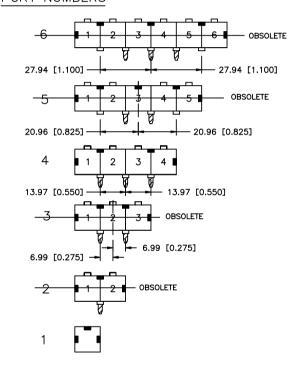
☐ INDICATES GROUNDING TAB ON THE FRONT OF PRODUCT (SEE SHEET 1)

INDICATES GROUNDING LEG ON THE BACK OF PRODUCT (VIEW B)

PORT NUMBERS



PORT NUMBERS



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